

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5178418

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NING GE	01/30/2017
STEVEN J. SIMSKE	01/31/2017
ANDREW E. FITZHUGH	01/31/2017
LIHUA ZHAO	01/31/2017
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<b>City:</b>	Houston
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	77070
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16075672
<b>CORRESPONDENCE DATA</b>	
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<b>Email:</b>	ipa.mail@hp.com, khoellger@anaqua.com
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<b>Address Line 2:</b>	INTELLECTUAL PROPERTY
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<b>ATTORNEY DOCKET NUMBER:</b>	84994927
<b>NAME OF SUBMITTER:</b>	JOHN E. NEMAZI
<b>SIGNATURE:</b>	/John E. Nemazi/
<b>DATE SIGNED:</b>	10/09/2018
<b>Total Attachments: 4</b>	
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HP Inc.  
3390 E. Harmony Road  
Mail Stop 36  
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 84571818

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPDC), and to its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPDC, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled:

BUILD MATERIAL PARTICLE FUSING IN A CHAMBER CONTAINING VAPOR

Filing Date: 06-AUG-2018

Application No.: 16/075,672

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent of any countries thereto which may be granted thereon or therefrom; and any reissues, or reexaminations, or extensions of said Patent.

I/we additionally authorize HPDC to file applications in my/our name for Patent in any country, to be held and enjoyed by HPDC, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Patent for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the Record ID and title set forth above, as soon as the same shall have been made known to them.

IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

  
Inventor's Signature

2018.08.07  
Date

Ning

GE

First/Middle Name

Last Name

Inventor's Signature

Date

Steven J.

SIMSKE

First/Middle Name


Last Name

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Mail Stop 35  
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 84571818

ASSIGNMENT OF PATENT APPLICATION (cont.)

 \_\_\_\_\_  
Inventor's Signature Date 1/31/2017

Andrew R. FITZHUGH  
First/Middle Name Last Name

\_\_\_\_\_  
Inventor's Signature Date

Lihua ZHAO  
First/Middle Name Last Name

\_\_\_\_\_  
Inventor's Signature Date

\_\_\_\_\_  
First/Middle Name Last Name

\_\_\_\_\_  
Inventor's Signature Date

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Inventor's Signature

Date

Ning

GE

First/Middle Name

Last Name

Steven J. Simske

Inventor's Signature

31 January 2017

Date

Steven J.

SIMSKE

First/Middle Name

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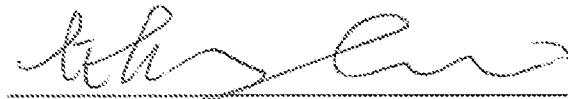
PATENT APPLICATION

RECORD ID: 84571818

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Andrew E. FITZHUGH  
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1/31/2017  
Date

Lihua ZHAO  
First/Middle Name Last Name

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

First/Middle Name Last Name

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

First/Middle Name Last Name

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